

Appl. No. 10/728,150
Amdt. dated March 12, 2007
Reply to Office action of December 12, 2006

In The Claims:

1-230. (canceled)

5 231. (currently amended) A circuit component comprising:

a first die having a top surface at a horizontal level;

~~a bottommost metal patterned wiring layer over said horizontal level, wherein said patterned wiring layer comprises a portion across a side of said die; extending to a place not over said first die, wherein said bottommost metal layer is connected to said first die;~~

10 and

a first polymer layer over said horizontal level, wherein said first polymer layer is the only one polymer layer between said first die and said patterned wiring layer, said patterned wiring layer being connected to said first die through an opening in said first polymer layer;

15 a passive device over said horizontal level; and:

a second polymer layer over said passive device.

20 232. (previously presented) The circuit component in claim 231 further comprising a substrate joined with said first die, wherein said substrate is under said horizontal level.

233. (previously presented) The circuit component in claim 232, wherein said substrate comprises polymer.

25 234. (previously presented) The circuit component in claim 232, wherein said substrate comprises resin.

235. (previously presented) The circuit component in claim 232, wherein said substrate comprises imide.

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236. (previously presented) The circuit component in claim 232, wherein said substrate comprises plastic.

237. (previously presented) The circuit component in claim 232, wherein said
5 substrate comprises thermosetting plastic.

Claims 238-243 (canceled)

244. (currently amended) The circuit component in claim ~~231, 243~~, wherein said
10 ~~first polymer insulating~~-layer comprises polyimide (PI).

245. (currently amended) The circuit component in claim ~~231, 243~~, wherein said
~~first polymer insulating~~-layer comprises benzocyclobutene (BCB).

246. (currently amended) The circuit component in claim ~~231, 243~~, wherein said
15 ~~first polymer insulating~~-layer comprises a porous structure.

Claims 247-255 (canceled)

256. (currently amended) The circuit component in claim ~~231, 255~~, wherein said
20 ~~second polymer insulating~~-layer comprises polyimide (PI).

257. (currently amended) The circuit component in claim ~~231, 255~~, wherein said
25 ~~second polymer insulating~~-layer comprises benzocyclobutene (BCB).

258. (currently amended) The circuit component in claim ~~231, 255~~, wherein said
~~second polymer insulating~~-layer comprises a porous structure.

259. (previously presented) The circuit component in claim 231, wherein said top

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surface comprises multiple pads.

260. (currently amended) The circuit component in claim 231, wherein said
patterned wiring metal layer comprises a portion connecting multiple internal circuits of
5 said first die.

261. (previously presented) The circuit component in claim 260, wherein said
portion is used to transmit a signal.

10 262. (previously presented) The circuit component in claim 260, wherein said
portion is used to provide a power voltage.

263. (previously presented) The circuit component in claim 260, wherein said
portion is used to provide a ground voltage.

15 264. (currently amended) The circuit component in claim 231 further comprising a
second die having a top surface at said horizontal level, ~~said bottommost metal layer~~
~~being over said second die~~, wherein said patterned wiring bottommost metal layer
comprises a portion connecting said first die and said second die.

20 265. (previously presented) The circuit component in claim 231 further
comprising a film layer around said first die.

25 266. (previously presented) The circuit component in claim 265, wherein said film
layer comprises polymer.

267. (previously presented) The circuit component in claim 265, wherein said film
layer comprises epoxy.

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268. (currently amended) The circuit component in claim 265, wherein said film layer has a top surface at said horizontal level, ~~substantially coplanar with said top surface.~~

5 269. (previously presented) The circuit component in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises solder.

270. (previously presented) The circuit component in claim 231 further comprising a bump over said horizontal level, wherein said bump comprises gold.
10

271. (previously presented) The circuit component in claim 231, wherein said passive device comprises a resistor.

272. (previously presented) The circuit component in claim 231, wherein said
15 passive device comprises a capacitor.

273. (previously presented) The circuit component in claim 231, wherein said passive device comprises an inductor.

20 274. (previously presented) The circuit component in claim 231, wherein said passive device comprises a filter.

275. (previously presented) The circuit component in claim 231, wherein said passive device comprises a waveguide.
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276. (previously presented) The circuit component in claim 231, wherein said passive device comprises a micro electronic mechanical sensor (MEMS).

277. (currently amended) The circuit component in claim 231, wherein said

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passive device is not directly over said first die.

Claim 278 (canceled)

- 5 279. (currently amended) The circuit component in claim 231, wherein said passive device is connected to said first die.

Claims 280-319. (canceled)

- 10 320. (new) The circuit component in claim 231, wherein said patterned circuit layer comprises copper.